

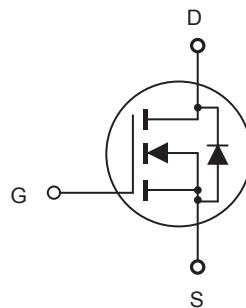


CED20N02/CEU20N02

N-Channel Enhancement Mode Field Effect Transistor

FEATURES

- 20V, 18A, $R_{DS(ON)} = 42m\Omega$ @ $V_{GS} = 4.5V$.
 $R_{DS(ON)} = 75m\Omega$ @ $V_{GS} = 2.5V$.
- Super high dense cell design for extremely low $R_{DS(ON)}$.
- High power and current handing capability.
- Lead free product is acquired.
- TO-251 & TO-252 package.



ABSOLUTE MAXIMUM RATINGS $T_C = 25^\circ C$ unless otherwise noted

Parameter	Symbol	Limit	Units
Drain-Source Voltage	V_{DS}	20	V
Gate-Source Voltage	V_{GS}	± 12	V
Drain Current-Continuous	I_D	18	A
Drain Current-Pulsed ^a	I_{DM}	72	A
Maximum Power Dissipation @ $T_C = 25^\circ C$ - Derate above $25^\circ C$	P_D	32 0.25	W W/ $^\circ C$
Operating and Store Temperature Range	T_J, T_{stg}	-55 to 150	$^\circ C$

Thermal Characteristics

Parameter	Symbol	Limit	Units
Thermal Resistance, Junction-to-Case	R_{JC}	4	$^\circ C/W$
Thermal Resistance, Junction-to-Ambient	R_{JA}	50	$^\circ C/W$



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Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Test Condition	Min	Typ	Max	Units
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	20			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 20\text{V}, V_{\text{GS}} = 0\text{V}$		1		μA
Gate Body Leakage Current, Forward	I_{GSSF}	$V_{\text{GS}} = 12\text{V}, V_{\text{DS}} = 0\text{V}$		100		nA
Gate Body Leakage Current, Reverse	I_{GSSR}	$V_{\text{GS}} = -12\text{V}, V_{\text{DS}} = 0\text{V}$		-100		nA
On Characteristics^b						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}} = V_{\text{DS}}, I_D = 250\mu\text{A}$	0.5		1.5	V
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 4.5\text{V}, I_D = 8\text{A}$		32	42	$\text{m}\Omega$
		$V_{\text{GS}} = 2.5\text{V}, I_D = 6.6\text{A}$		52	75	$\text{m}\Omega$
Forward Transconductance	g_{FS}	$V_{\text{DS}} = 10\text{V}, I_D = 8\text{A}$		15		S
Dynamic Characteristics^c						
Input Capacitance	C_{iss}	$V_{\text{DS}} = 15\text{V}, V_{\text{GS}} = 0\text{V}, f = 1.0 \text{ MHz}$		515		pF
Output Capacitance	C_{oss}			220		pF
Reverse Transfer Capacitance	C_{rss}			80		pF
Switching Characteristics^c						
Turn-On Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 10\text{V}, I_D = 1\text{A}, V_{\text{GS}} = 4.5\text{V}, R_{\text{GEN}} = 6\Omega$		19		ns
Turn-On Rise Time	t_r			13		ns
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$			48		ns
Turn-Off Fall Time	t_f			9		ns
Total Gate Charge	Q_g	$V_{\text{DS}} = 10\text{V}, I_D = 8\text{A}, V_{\text{GS}} = 4.5\text{V}$		10		nC
Gate-Source Charge	Q_{gs}			3		nC
Gate-Drain Charge	Q_{gd}			2		nC
Drain-Source Diode Characteristics and Maximum Ratings						
Drain-Source Diode Forward Current	I_S				20	A
Drain-Source Diode Forward Voltage ^b	V_{SD}	$V_{\text{GS}} = 0\text{V}, I_S = 4\text{A}$			1.3	V

Notes :

- a.Repetitive Rating : Pulse width limited by maximum junction temperature
- b.Pulse Test : Pulse Width < 300μs, Duty Cycle < 2%.
- c.Guaranteed by design, not subject to production testing.

IGBT

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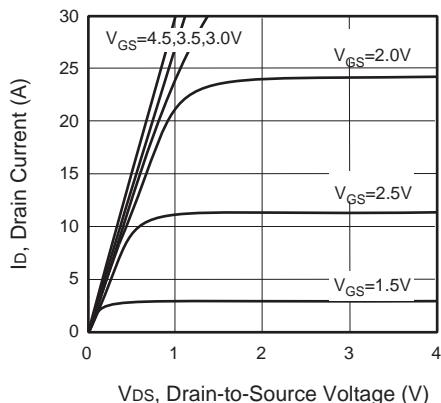


Figure 1. Output Characteristics

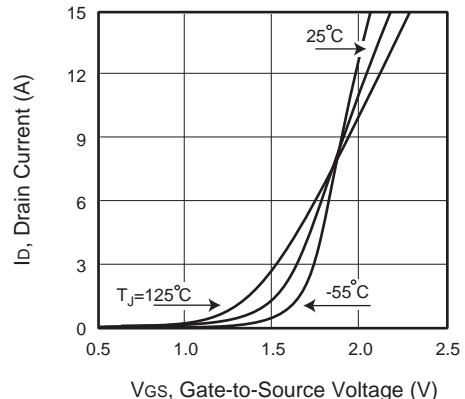


Figure 2. Transfer Characteristics

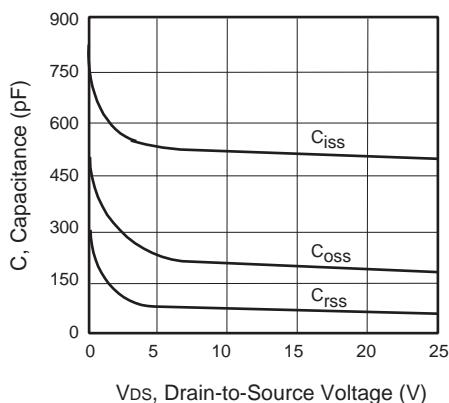


Figure 3. Capacitance

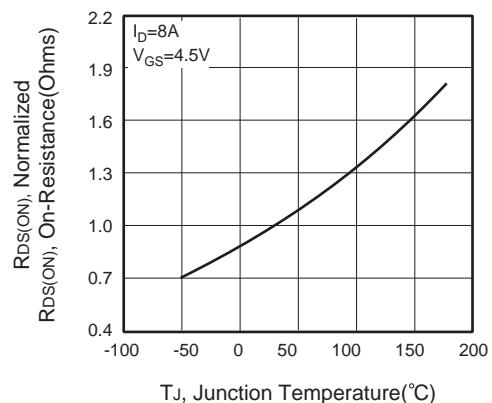


Figure 4. On-Resistance Variation with Temperature

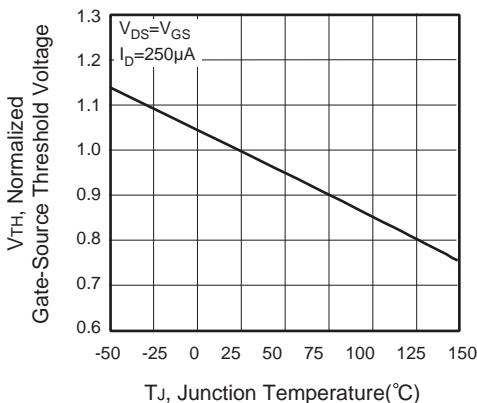


Figure 5. Gate Threshold Variation with Temperature

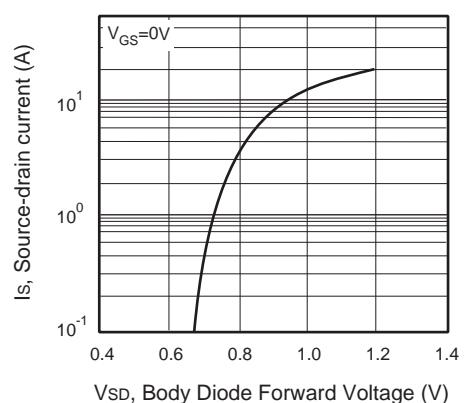


Figure 6. Body Diode Forward Voltage Variation with Source Current



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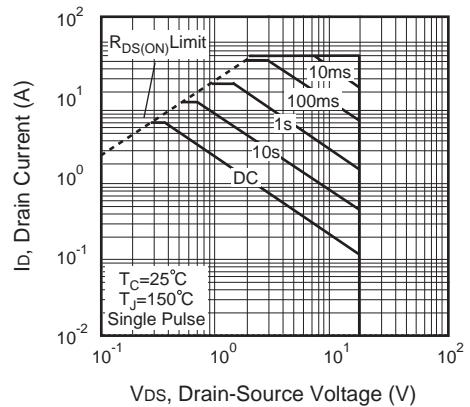
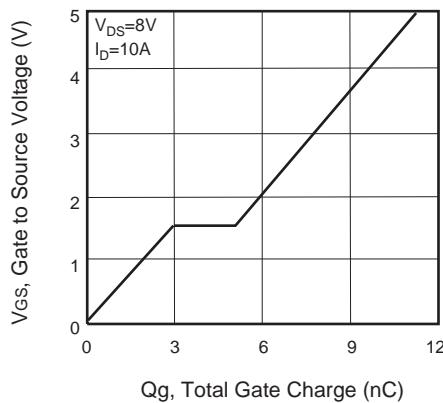


Figure 7. Gate Charge

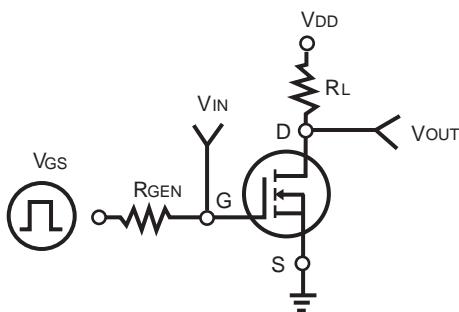


Figure 9. Switching Test Circuit

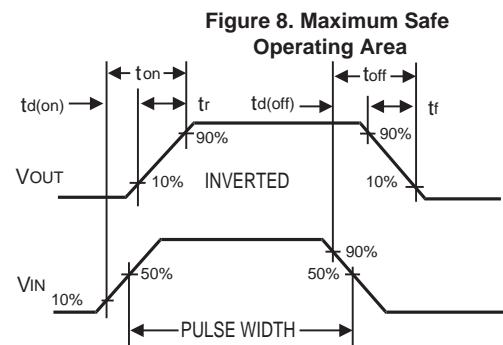


Figure 10. Switching Waveforms

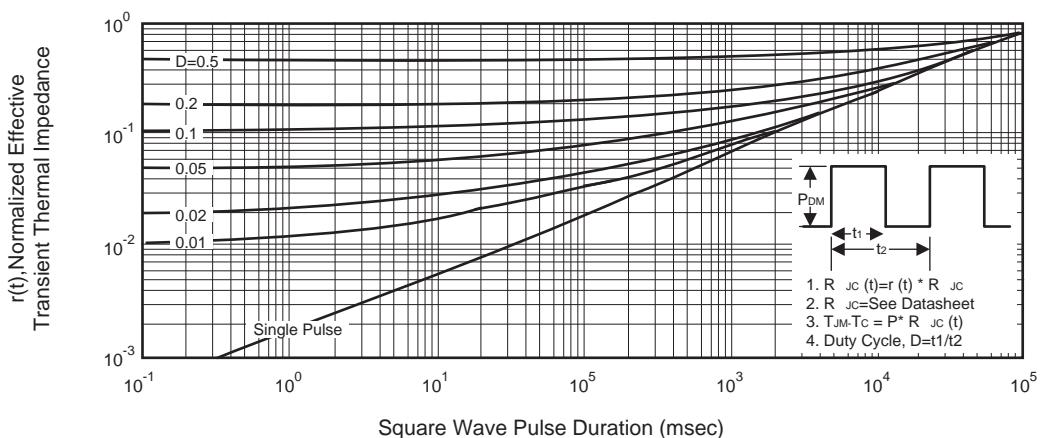


Figure 11. Normalized Thermal Transient Impedance Curve